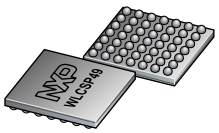

SOT2060-1

WLCSP49, wafer level chip scale package, 49 terminals, 0.35 mm pitch, 2.56 mm x 2.46 mm x 0.365 mm body (backside coating included)

7 May 2020 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP49
Package type industry code	WLCSP49
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	20-04-2020
Manufacturer package code	98ASA01596D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.53	2.56	2.59	mm
package width	2.43	2.46	2.49	mm
seated height	-	0.365	0.395	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	49	-	

WLCSP49, wafer level chip scale package, 49 terminals, 0.35 mm pitch, 2.56 mm x 2.46 mm x 0.365 mm body (backside coating included)

2 Package outline

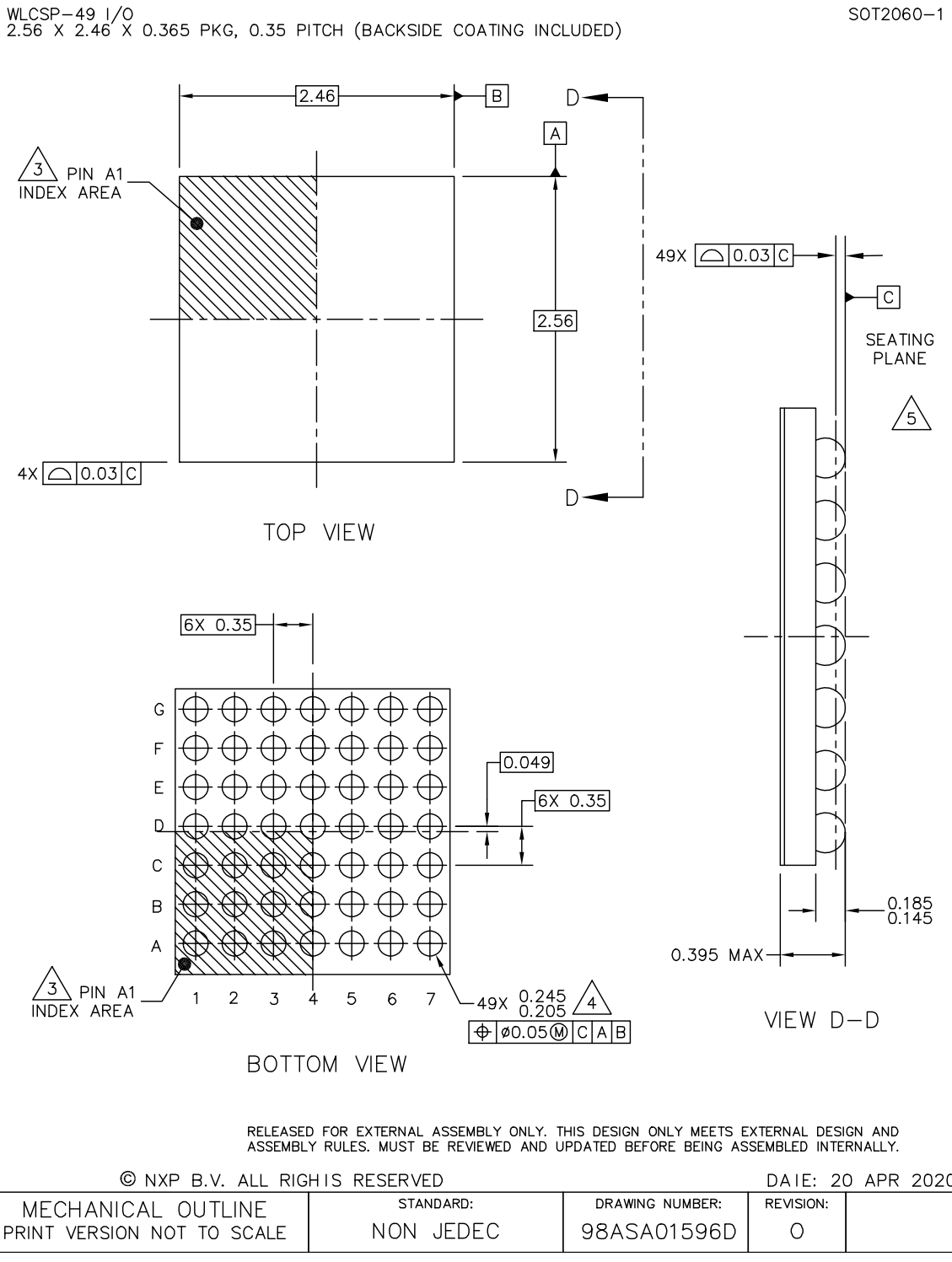

Figure 1. Package outline WLCSP49 (SOT2060-1)

3 Soldering

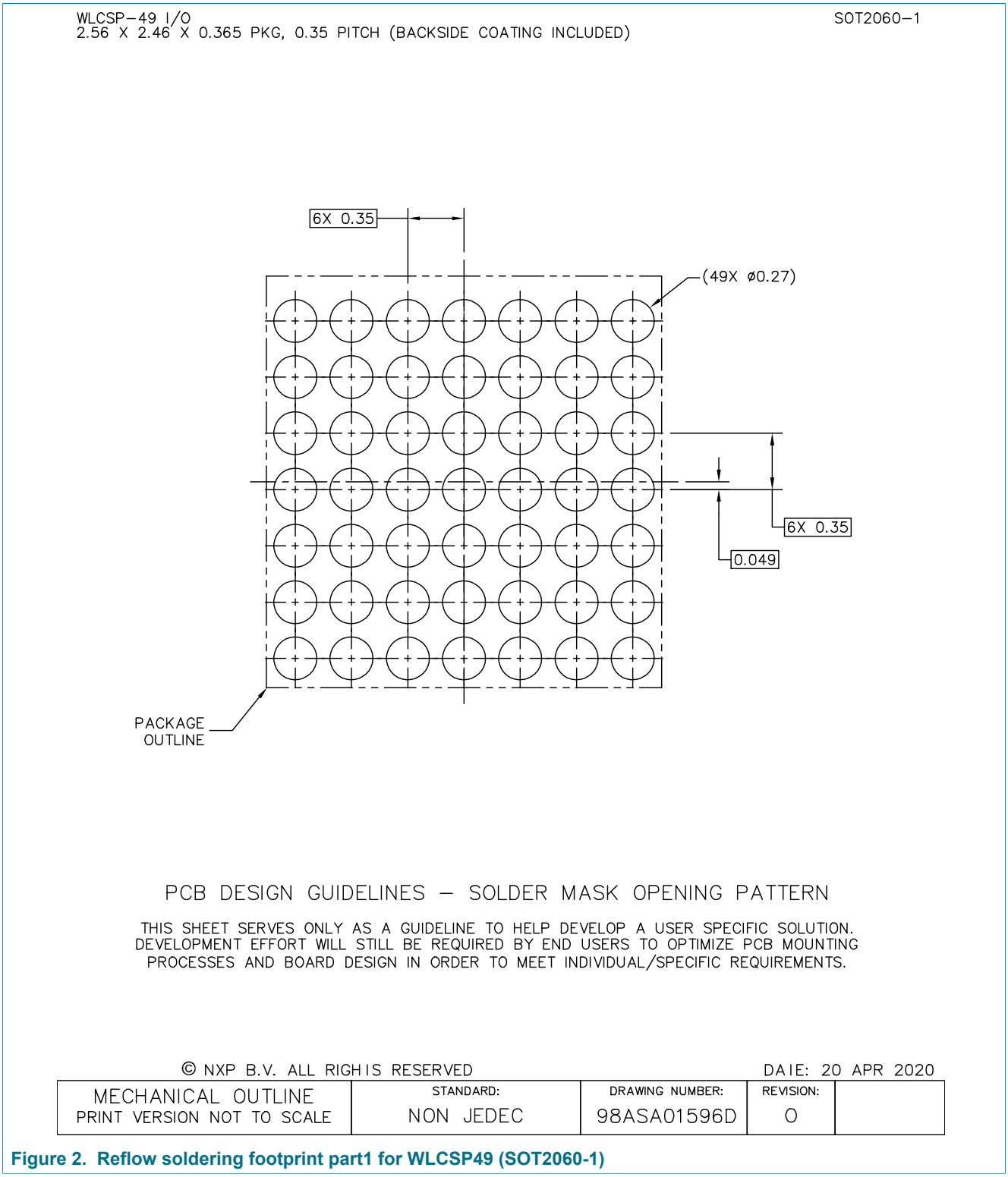

Figure 2. Reflow soldering footprint part1 for WLCSP49 (SOT2060-1)

WLCSP49, wafer level chip scale package, 49 terminals, 0.35 mm pitch, 2.56 mm x 2.46 mm x 0.365 mm body (backside coating included)

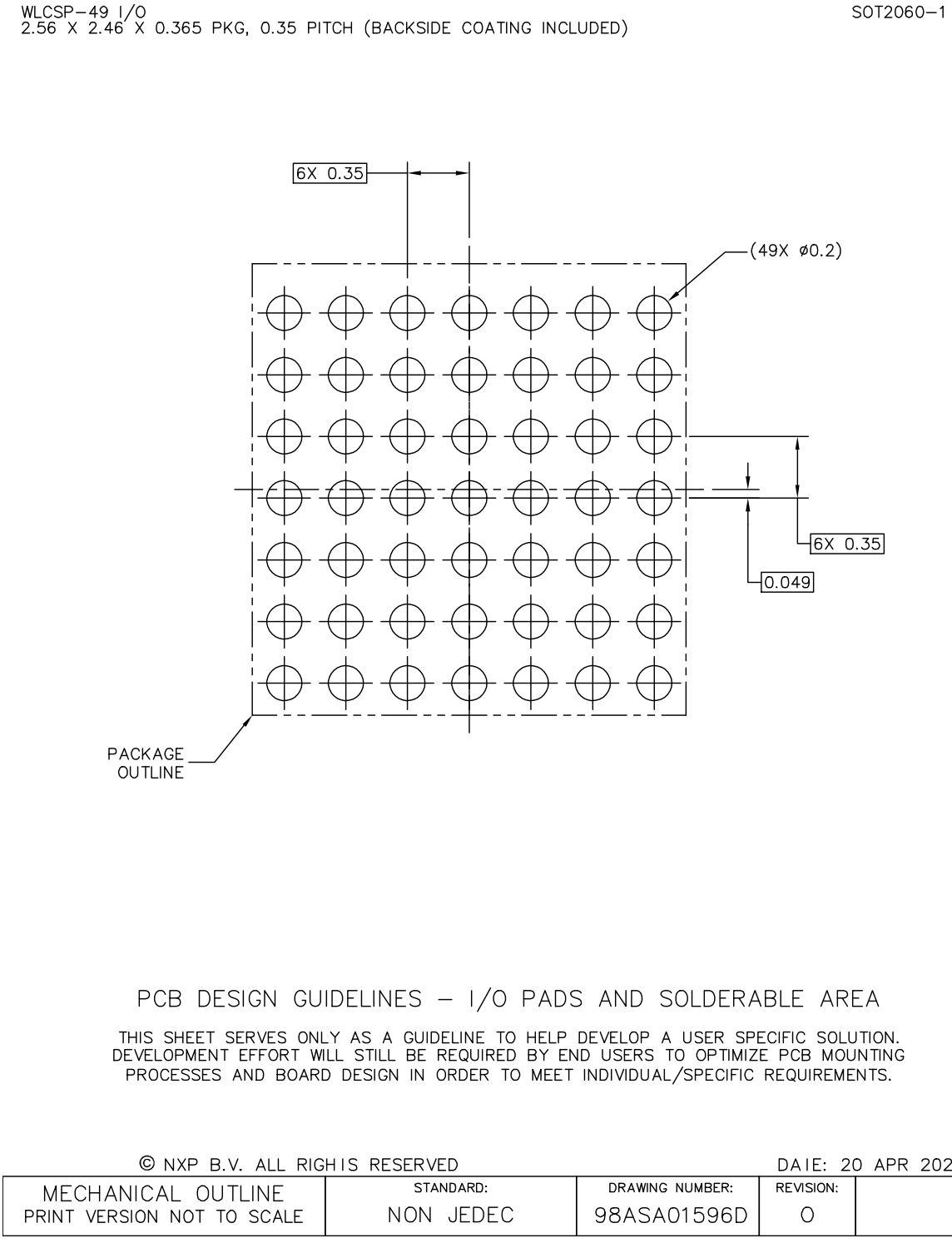

Figure 3. Reflow soldering footprint part2 for WLCSP49 (SOT2060-1)

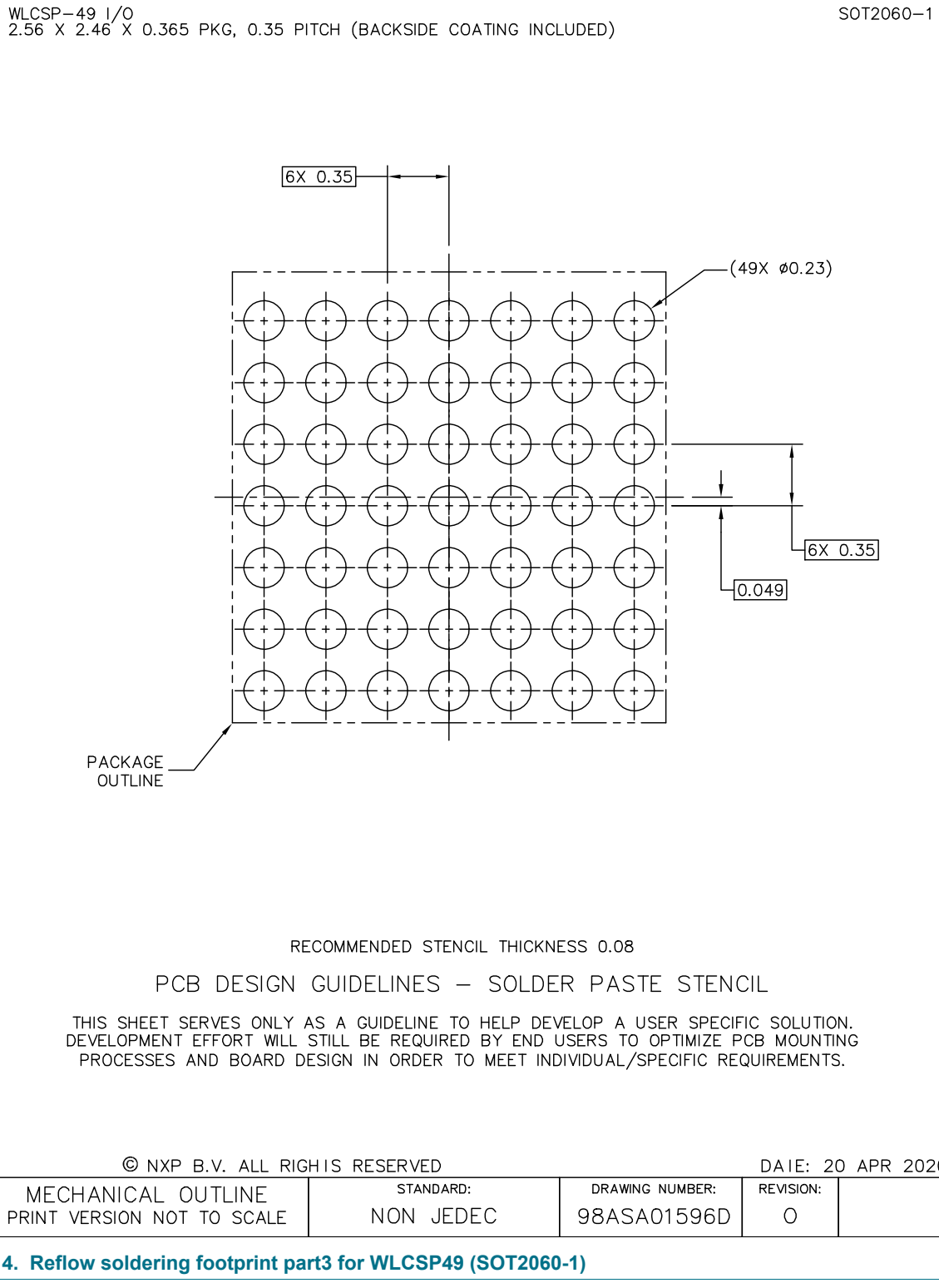

Figure 4. Reflow soldering footprint part3 for WLCSP49 (SOT2060-1)

WLCSP49, wafer level chip scale package, 49 terminals, 0.35 mm pitch, 2.56 mm x 2.46 mm x 0.365 mm body (backside coating included)

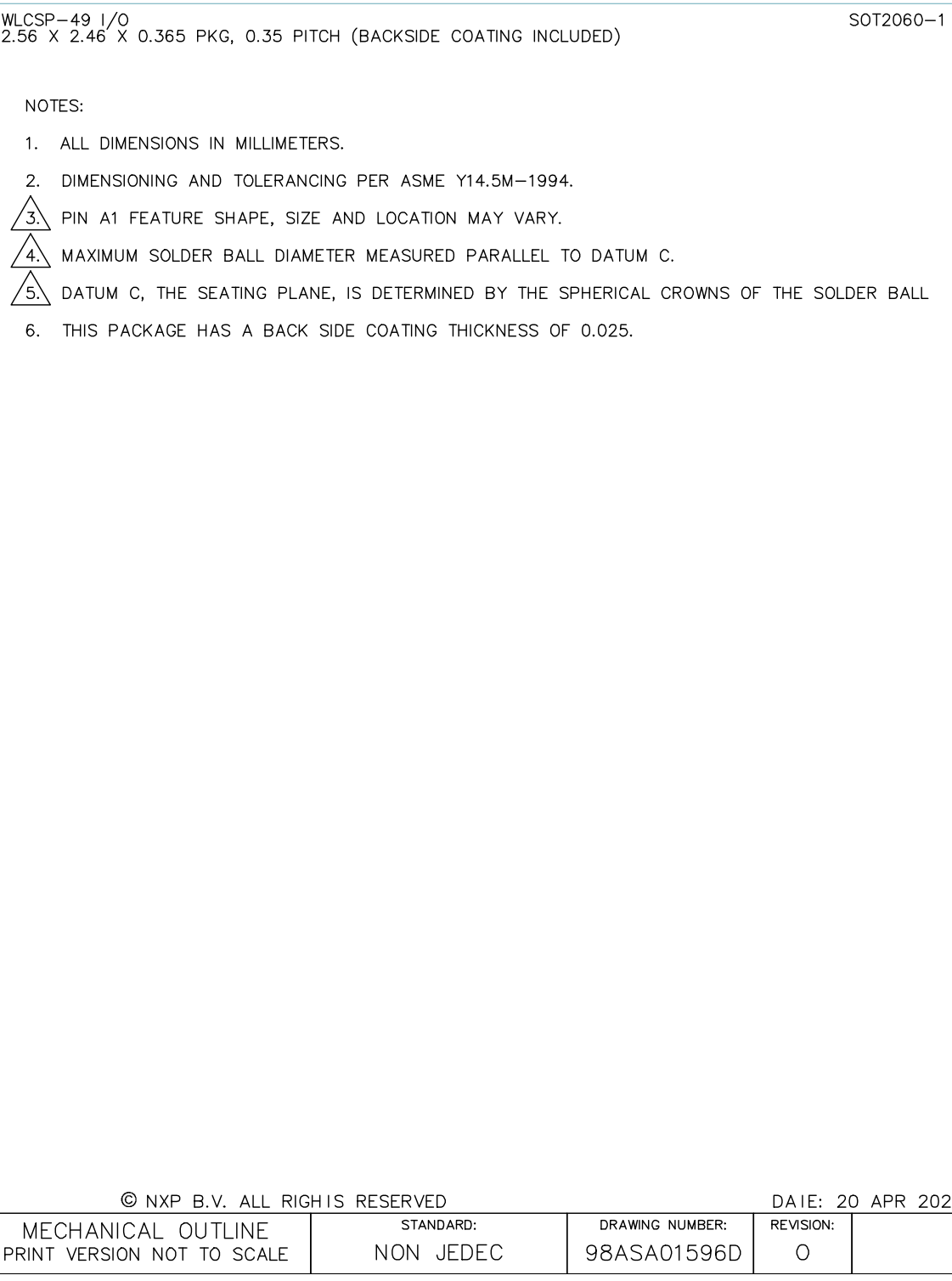

Figure 5. Package outline note WLCSP49 (SOT2060-1)

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WLCSP49, wafer level chip scale package, 49 terminals, 0.35 mm pitch, 2.56 mm x 2.46 mm x 0.365 mm body (backside coating included)

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